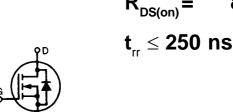


HiPerFET[™] Power MOSFETs IXFR 180N10 ISOPLUS247[™]

(Electrically Isolated Back Surface)

Single MOSFET Die

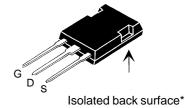
Preliminary data



Symbol	Test Conditions	Maximum F	Maximum Ratings		
V _{DSS} V _{DGR}	$T_{_{\rm J}}$ = 25°C to 150°C $T_{_{\rm J}}$ = 25°C to 150°C; $R_{_{\rm GS}}$ = 1 MΩ	100 100	V		
V _{GS} V _{GSM}	Continuous Transient	±20 ±30	V		
D25 D(RMS) DM AR	$T_{\rm c} = 25^{\circ}{\rm C}$ (MOSFET chip capability) External lead (current limit) $T_{\rm c} = 25^{\circ}{\rm C}$, Note 1 $T_{\rm c} = 25^{\circ}{\rm C}$	165 76 720 180	A A A		
E _{AR}	T _c = 25°C T _c = 25°C	60 3	mJ J		
dv/dt	$I_{_{S}} \leq I_{_{DM}}$, di/dt \leq 100 A/ μ s, $V_{_{DD}} \leq V_{_{DSS}}$ $T_{_{J}} \leq$ 150°C, $R_{_{G}} = 2~\Omega$	5	V/ns		
$\overline{P_{D}}$	T _c = 25°C	400	W		
T _J T _{JM} T _{stg}		-55 +150 150 -55 +150	°C °C °C		
T _L	1.6 mm (0.063 in.) from case for 10 s	300	°C		
V _{ISOL}	50/60 Hz, RMS t = 1 min	2500	V~		
Weight		5	g		

Symbol	Test Conditions	Characteristic Values (T _J = 25°C, unless otherwise specified) min. typ. max.			
V _{DSS}	$V_{GS} = 0 \text{ V}, I_D = 3\text{mA}$	1	00		V
V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 8mA$		2.0		4.0 V
I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$				±100 nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	$T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$			100 μA 2 mA
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_{D} = 90\text{A}$ Note 1				8 mΩ

ISOPLUS 247™



G = Gate D = DrainS = Source

* Patent pending

Features

- Silicon chip on Direct-Copper-Bond substrate
- High power dissipation
- Isolated mounting surface
- 2500V electrical isolation
- Low drain to tab capacitance(<25pF)
- Low $R_{DS (on)} HDMOS^{TM} process$
- Rugged polysilicon gate cell structure
- * Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- · Fast intrinsic Rectifier

Applications

- DC-DC converters
- · Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control

Advantages

- · Easy assembly
- · Space savings
- High power density



Symbol	Test Conditions	Characteristic Values $(T_J = 25^{\circ}C, \text{ unless otherwise specified})$ min. typ. max.				
				typ.	max.	
g _{fs}	$V_{DS} = 10 \text{ V}; I_{D} = 90 \text{A}$	Note 2	60	90		S
C _{iss})			9400		pF
C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f =$	= 1 MHz		3200		pF
\mathbf{C}_{rss}	J			1660		pF
t _{d(on)})			50		ns
t _r	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot \text{V}$	$_{\rm DSS}$, $I_{\rm D} = 90A$		90		ns
$\mathbf{t}_{d(off)}$	$R_{\rm G} = 1 \Omega$ (External),			140		ns
t _f	J			65		ns
Q _{g(on)})			400		nC
\mathbf{Q}_{gs}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot \text{ V}$	$_{\rm DSS}$, $I_{\rm D} = 90A$		65		nC
\mathbf{Q}_{gd}	J			220		nC
R _{thJC}		·			0.30	K/W
R _{thCK}		·		0.15		K/W

Source-Drain Diode		Characteristic Values (T ₁ = 25°C, unless otherwise specified)				
Symbol	Test Conditions	min.	typ.	max.		
I _s	V _{GS} = 0 V			180	Α	
I _{sm}	Repetitive; pulse width limited by T _{JM}			720	Α	
V _{SD}	$I_F = 100A, V_{GS} = 0 V, Note 1$			1.5	V	

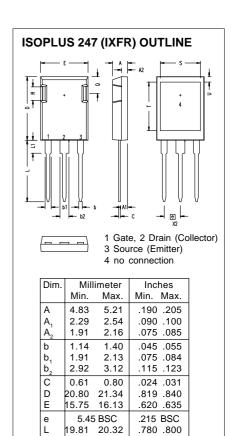
Note: 1. Pulse width limited by T_{JM}

 \mathbf{t}_{rr}

 \mathbf{Q}_{RM}

2. Pulse test, $t \le 300 \ \mu s$, duty cycle $d \le 2 \ \%$

 $I_F = 50A, -di/dt = 100 A/\mu s, V_R = 100 V$



L1

Q

R

S

3.81

5.59

4.32

13.21

15.75

4.32

6.20

4.83

13.72

3.03

16.26

.150 .170

.220 .244

.170 .190

.520 .540

.620 .640

.065 .080

250

1.1

13

ns

μC A

